ARES-1980 Series

Fanless Rugged Controller with 11th Gen. Intel[®] Core[™] i7/i5/i3 Processor

User's Manual

Version 1.1



P/N: 4016198000110P

Revision History

Version	Date	Description
1.0	2021.12	Initial release
1.1	2023.01	- Revise connector type of (21) IO1 on page 21
		- Add 2.2.4. Top Side View and 2.2.5 LED Indicator
		Status

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Copyright Notice

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Declaration of Conformity

CE

The CE symbol on your product indicates that it is in compliance with the directives of the Union European (EU). A Certificate of Compliance is available by contacting Technical Support.

This product has passed the CE test for environmental specifications when shielded cables are used for external wiring. We recommend the use of shielded cables. This kind of cable is available from ARBOR. Please contact your local supplier for ordering information.

Warning

This is a class A product. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

FCC Class A

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) This device must accept any interference received, including interference that may cause undesired operation.

NOTE:

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

RoHS

ARBOR Technology Corp. certifies that all components in its products are in compliance and conform to the European Union's Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive 2002/95/EC.

The above mentioned directive was published on 2/13/2003. The main purpose of the directive is to prohibit the use of lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB), and polybrominated diphenyl ethers (PBDE) in electrical and electronic products. Member states of the EU are to enforce by 7/1/2006.

ARBOR Technology Corp. hereby states that the listed products do not contain unintentional additions of lead, mercury, hex chrome, PBB or PBDB that exceed a maximum concentration value of 0.1% by weight or for cadmium exceed 0.01% by weight, per homogenous material. Homogenous material is defined as a substance or mixture of substances with uniform composition (such as solders, resins, plating, etc.). Lead-free solder is used for all terminations (Sn(96-96.5%), Ag(3.0-3.5%) and Cu(0.5%)).

SVHC / REACH

To minimize the environmental impact and take more responsibility to the earth we live, Arbor hereby confirms all products comply with the restriction of SVHC (Substances of Very High Concern) in (EC) 1907/2006 (REACH --Registration, Evaluation, Authorization, and Restriction of Chemicals) regulated by the European Union.

All substances listed in SVHC < 0.1 % by weight (1000 ppm)

Important Safety Instructions

Read these safety instructions carefully

- 1. Read all cautions and warnings on the equipment.
- 2. Place this equipment on a reliable surface when installing. Dropping it or letting it fall may cause damage
- 3. Make sure the correct voltage is connected to the equipment.
- 4. For pluggable equipment, the socket outlet should be near the equipment and should be easily accessible.
- 5. Keep this equipment away from humidity.
- 6. The openings on the enclosure are for air convection and protect the equipment from overheating. DO NOT COVER THE OPENINGS.
- 7. Position the power cord so that people cannot step on it. Do not place anything over the power cord.
- 8. Never pour any liquid into opening. This may cause fire or electrical shock.
- 9. Never open the equipment. For safety reasons, the equipment should be opened only by qualified service personnel.
- 10. If one of the following situations arises, get the equipment checked by service personnel:
 - The power cord or plug is damaged.
 - b. Liquid has penetrated into the equipment.
 - c. The equipment has been exposed to moisture.
 - d. The equipment does not work well, or you cannot get it to work according to the user's manual.
 - e. The equipment has been dropped or damaged.
 - f. The equipment has obvious signs of breakage.
- 11. Keep this User's Manual for later reference.

Warning

The Box PC and its components contain very delicately Integrated Circuits (IC). To protect the Box PC and its components against damage caused by static electricity, you should always follow the precautions below when handling it:

- Disconnect your Box PC from the power source when you want to work on the inside.
- 2. Use a grounded wrist strap when handling computer components.
- 3. Place components on a grounded antistatic pad or on the bag that came with the Box PC, whenever components are separated from the system.

Lithium Battery Replacement

Incorrect replacement of the lithium battery may lead to a risk of explosion.

The lithium battery must be replaced with an identical battery or a battery type recommended by the manufacturer.

Do not throw lithium batteries into the trash can. It must be disposed of in accordance with local regulations concerning special waste.

Technical Support

If you have any technical difficulties, please consult the user's manual first at: https://www.arbor-technology.com

Please do not hesitate to call or e-mail our customer service when you still cannot find out the answer.

https://www.arbor-technology.com

E-mail:info@arbor.com.tw

Warranty

This product is warranted to be in good working order for a period of one year from the date of purchase. Should this product fail to be in good working order at any time during this period, we will, at our option, replace or repair it at no additional charge except as set forth in the following terms. This warranty does not apply to products damaged by misuse, modifications, accident or disaster.

Vendor assumes no liability for any damages, lost profits, lost savings or any other incidental or consequential damage resulting from the use, misuse of, or inability to use this product. Vendor will not be liable for any claim made by any other related party.

Vendors disclaim all other warranties, either expressed or implied, including but not limited to implied warranties of merchantability and fitness for a particular purpose, with respect to the hardware, the accompanying product's manual(s) and written materials, and any accompanying hardware. This limited warranty gives you specific legal rights.

Return authorization must be obtained from the vendor before returned merchandise will be accepted. Authorization can be obtained by calling or faxing the vendor and requesting a Return Merchandise Authorization (RMA) number. Returned goods should always be accompanied by a clear problem description.

Chapter 1

Introduction

1.1. Features

- Onboard Intel® Core™ i Processor (Tiger Lake UP3)
- Support 2 x 260-pin DDR4 SO-DIMM sockets
- Support 5G (Sub-6G) module, M.2 NVMe SSD Gen3x4, USB 3.2 Gen2, and 2.5 GbE LAN
- Rich I/O: 4 x COM/ 3 x 2.5GbE LAN/ 4 x USB3.2 Gen 2/ Remote control PWR
- Support Triple-display (DVI-D/HDMI/DP)
- Wide Power Input: 9~36 VDC
- Power on/off delay control / configurable ignition power control
- Support DirectX 12

1.2. About this Manual

This manual is meant for the experienced users and integrators with hardware knowledge of personal computers. If you are not sure about the description in this manual, consult your vendor before further handling.

We recommend that you keep one copy of this manual for the quick reference for any necessary maintenance in the future. Thank you for choosing ARBOR products.

1.3. Specifications

System		
СРИ	Soldered onboard Intel® i7/ i5/ i3 Processor (Default: i5 CPU Tiger Lake-U)	
Memory	2 x 260-pin DDR4 SO-DIMM sockets, supporting 3200MHz SDRAM up to 64GB	
Chipset	SoC	
Graphics	Intel® Iris® Xe Graphics	
LAN Chipset	2 x Intel® i211AT PCIe controller 1 x Intel® 225LM PCIe controller	
Watchdog Timer	1~255 levels reset	
I/O		
Serial Port	2 x RS232 (DB-9 male connector) 2 x RS232(Default)/422/485 (RI/5V/12V) (DB-9 male connector/ Switch via BIOS)	
4 x USB-A 3.2 Gen2 (2 w/ independent full speed) 1 x USB-A 2.0 onboard for encryption dongle (Type A)		
LAN	2 x RJ-45 ports for GbE LAN (PoE complies with IEEE802.3af) 1 x RJ-45 ports for 2.5 GbE LAN (iAMT support w/ i5/i7 skus)	
	1 x HDMI 2.0b, up to 3840x2160@60Hz	
Video Port	1 x DisplayPort 1.4, up to 3840x2160@60Hz	
	1 x DVI-D, up to 1920x1080@60Hz	
Audio	1 x Mic-in & 1 x Line out	
	1 x full mPCle slot (PCle x1+ USB2.0, Full size) w/ 1 x nano SIM card slot	
Expansion Bus	1 x M.2 B-Key 2242/3042/3052 (PCIe x2 + USB3.0) w/ 2 x nano SIM card slots supporting 5G/LTE module	
	1 x M.2 E-Key 2230 (CNVi + USB 2.0) slot for WiFi /BT **Support CNVi modules only**	
Digital I/O	8 x DI & 8 x DO w/ 1.5KV isolation	
Multi-Serial Bus	I ² C/SPI/UART/GPIO (w/ 3.3 or 5V) via DB-26	
Others	10 x Antenna Holes are reserved	

Storage				
	1 x M.2 M-Key 2242/2280			
Туре	(PCIe Gen III x4 + SATAIII)			
1,400	1 x 2.5" HDD/SSD tray			
	(SATA III + SATA PWR connector)			
Environmental				
Operating Temp.	-20 ~ 60°C (-4 ~ 140°F), ambient w/ air flow			
Storage Temp.	-40 ~ 70°C (-40 ~ 158°F)			
Operating Humidity	10-95% @ 60°C (non-condensing)			
Vibration	5~500Hz 3 Grms X,Y,Z axis w/ SSD, according to IEC 60068-2-64			
	40G peak acceleration (11 m sec. duration), operation w/ SSD			
Shock	80G peak acceleration (11 m sec. duration), nonoperation w/ SSD			
	According to IEC 60068-2-27			
Qualification				
Certification CE/ FCC Class A				
Power Requireme	nt			
Power Input DC 9~36V (3-pin terminal block: V+, V-, GND)				
Max. Power Consumption	120W			
Remote Control	1x3-pin terminal block for remote control and PWR LED output			
Power Ignition	IGN +/-			
Mechanical				
Construction	Sheet Metal + Aluminum Alloy			
Mounting	Wall-mount (standard) DIN-rail or VESA mount (optional w/ CTOS bracket)			
Weight	3.7kg			
Dimensions (W x D x H)	210 x 180 x 70 mm			
OS Support				
Windows 10 IoT Ubuntu 18.04				

1.3. Inside the Package

Upon opening the package, carefully inspect the contents. If any of the items is missing or appears damaged, contact your local dealer or distributor. The package should contain the following items:



1 x ARES-1980



Terminal blocks:

2 x 10 Pin

2 x 3 Pin

1 x 2 Pin



1 x USB dongle bracket



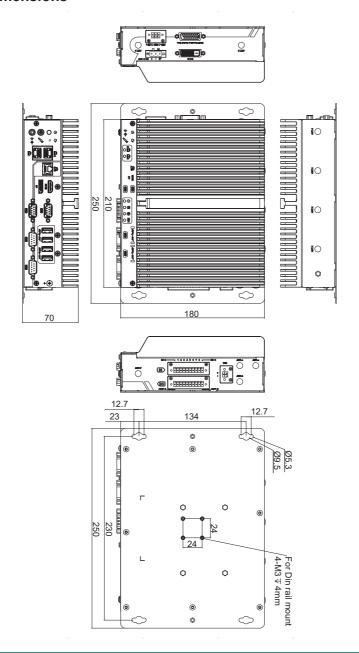
User's manual



Chapter 2

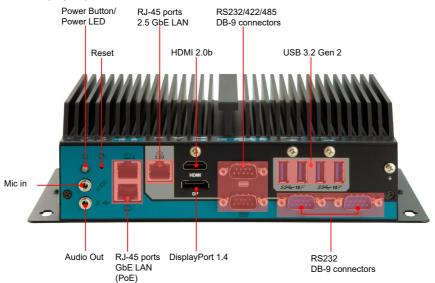
Getting Started

2.1. Dimensions



2.2. Overview

2.2.1. Front View



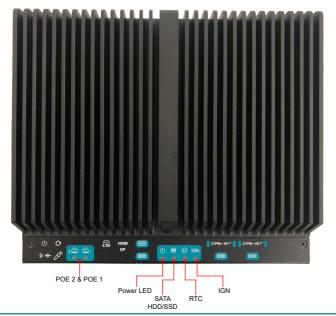
2.2.2. Left Side View



2.2.3. Right Side View



2.2.4. Top Side View



2.2.5. LED Indicator Status

LED Indicator	lcon	Blinking Mode	Status	
PWR	\bigcirc	Solid Green	System powered on	
SATA HDD/SSD		Flashing Red	Data transmitting	
RTC	(1 -)	Solid Red	RTC battery is low	
IGN	IGN	Flashing Green	IGN settings is detected	
IGN		Solid Green	Normal operating	
PoE 1	<u> </u>	Solid Amber	Active	
PoE 2 2 4		Solid ATTIDEL	Active	

2.3. Driver Installation Note

For operating system of Windows 10, please go to our website at **www.arbor-technology.com** and download the driver pack from the product page. Then unzip the downloaded file and follow the sequence below to install the drivers to prevent errors:

$\textbf{Chipset} \rightarrow \textbf{Graphic} \rightarrow \textbf{Audio} \rightarrow \textbf{Other drivers}$

The driver path is listed as below:

Windows 10

Driver	Path		
Chipset	\WIN10\Chipset\10.1.1.42\SetupChipset.exe		
LAN	\WIN10\Ethernet\PROWinx64.exe		
VGA	\WIN10\Graphics\Setup.exe		
Audio	\WIN10\AUDIO\0006-64bit_Win7_Win8_Win81_Win10_R279.exe		
ME	\WIN10\ME_11.6\SetupME.exe		

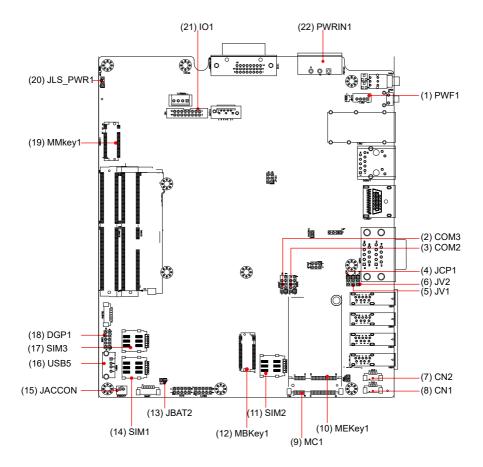


Chapter 3

Engine of the Computer

3.1. Boards Overview

The PCBs of the computer varies according to the models. The following table lists the PCBs of each model:



Connectors

Label	Description
(1) PWF1	Power button and Power LED Connector
(2) COM3	COM port for 9pin D-SUB
(3) COM2	COM port for 9pin D-SUB
(4) JCP1	Power selection for COM port
(5) JV1	COM1 function
(6) JV2	COM2 function
(7) CN2	USB2.0 wafer connector
(8) CN1	USB2.0 wafer connector
(9) MC1	PCI Express Mini-card socket
(10) MEKEY1	M.2 E-Key socket
(11) SIM2	Nano SIM card socket
(12) MBKEY1	M.2 B-Key socket
(13) JBAT2	Reset CMOS settings
(14) SIM1	Nano SIM card socket
(15) JACCON2	Acc mode selection for vehicles
(16) USB5	USB connector
(17) SIM3	Nano SIM card socket
(18) DGP1	External debug port
(19) MMKEY	M.2 M-Key socket
(20) JLS_PWR1	Multi Serial Bus power connector
(21) Multi Serial Bus	Multi Serial Bus connector
(22) PWRIN1	Power Input Terminal Block

3.2. Connectors

(1) PWF1

Function: Power button and Power LED Connector **Connector Type:** 2.00 mm pitch 1x4-pin one-wall connector

Pin Assignment:

Pin	Desc.	
1	PWR_IN_SW#	4 1
2	GND	
3	LED+	
4	NC	

(2)(3) COM2/3 (COM3/4 on front panel)

Function: RS232 DB9 connector

Connector Type: 2.00 mm pitch 2x5 pin box header

Pin Assignment:

	Pin	Desc.	Pin	Desc.
	1	DCD	2	RXD
RS232	3	TXD	4	DTR
K3232	5	GND	6	DSR
	7	RTS	8	CTS
	9	RI	10	NC



(4)JCP1

Function: Power selection for COM port

Jumper Type: Onboard 2.00mm-pitch 1x3-pin header

Short 1-2 COM_5V

Short 2-3 COM 12V

(5)(6)JV1/JV2

Function: RI/5V/12V (Pin 9) Selection for COM Port Jumper Type: Onboard 2.00mm-pitch 1x3-pin header

Setting: Pin

Pin Description

Short 1-2 RI (default)

Short 2-3 5V or 12V (depends on JCP1)

(7)(8) CN1/CN2

Function: USB2.0 Wafer

Connector Type: onboard Type 4pin wafer

 Pin Assignment:
 Pin Desc.

 1
 VCC5

 2
 DATA

 3
 DATA+

 4
 GND

(9) MC2

Function: PCI Express Mini-card Full socked

Connector Type: Onboard 0.8mm pitch 52-pin edge card connector.

Pin Assignment:



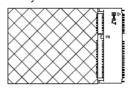
(10) MEKEY1

Function: M.2 E-Key socket (w/ CNVi+USB2.0) for

optional Wi-Fi/BT M.2 E-Key 2230 Socket

Connector Type: M.2 E-Key 2230 Socket **Pin Assignment:** The pin assignments conform to the

industry standard.



(11) SIM2

Function: SIM Card Socket
Connector Type: 6-pin SIM card socket

Pin Assignment:

Pin	Desc.	Pin	Desc	
C1	VCC	C2	RST	
C3	CLK	C5	GND	
C6	VPP	C7	I/O	



(12) MBKEY1

Function: M.2 B-Key socket (w/ PCle + USB 3.0 or

PCIe x2)(either one)

Connector Type: M.2 B-Key

Pin Assignment: The pin assignments conform to the

industry standard.

(13) JBAT2

Function: Clears/keeps CMOS

Jumper Type: 2.00 mm pitch 1x2-pin header

Setting:

Pin	Description		
Short	Clears CMOS	1 2	
Open	Keeps CMOS (default)	1 2	

(14) SIM1

Function: SIM Card Socket
Connector Type: 6-pin SIM card socket
Pin Assignment: Pin Dosc Pin

Pin	Desc.	Pin	Desc	
01	V/CC	00	DOT	
<u> </u>	VCC	<u> </u>	KSI	
C3	CLK	C5	GND	
C6	VPP	C7	I/O	



(15) JACCON2

Function Ignition Power Connector
Connector Type: Onboard 2x1-pin box connector

Pin Assignment:

Pin	Description	
1	Acc_ON	
2	GND	



(16) USB5

Function: Internal USB 2.0 connector Connector Type: USB2.0 Type-A connector

Pin Assignment: The Pin assignment conform to the industry

standard.

(17) SIM3

Function: SIM Card Socket Connector Type: 6-pin SIM card socket

Pin Assignment:

 Pin
 Desc.
 Pin
 Desc

 C1
 VCC
 C2
 RST

 C3
 CLK
 C5
 GND

 C6
 VPP
 C7
 I/O



(18) DGP1

Function: Debug port

Connector Type: 2.00mm-pitch 2x5-pin header

Pin Assignment:

Pin	Description	Pin	Description
1	24MHz Clock	2	GND
3	LPC_FRAME#	4	LPC_LAD0
5	PLTRST#	6	N.C
7	LPC_LAD3	8	LPC_LAD2
9	VCC3	10	LPC_LAD1



(19) MMKEY1

Function: M.2 M-Key Connector

Connector Type: M.2 75-pin M-Key connector for PCle x4/SATA-III SSD

storage, supporting 22x42 / 22x80 modules

Pin Assignment: The pin assignments conform to the industry standard.



(20)JLS_PWR1

Function: Multi Serial Bus power connector **Jumper Type:** Onboard 2.00mm-pitch 1x3-pin header

Setting: Pin Description

Short 1-2 5V(default)

Short 2-3 3.3V

(21) IO1

Function: Multi Serial Bus connector
Connector Type: 2.00mm-pitch 2x8-pin header

Pin Assignment:

Piı	n Description	Pin	Description
1	I2C0_SCL	2	I2C0_SDA
3	SPI_MISO	4	SPI_MOSI
5	SPI_CLK	6	SPI_CS#
7	LS_PWR	8	GND
	5V(default)/3.3V	0	GND
9	I2C1_SCL	10	I2C1_SDA
11	UART_TXD	12	UART_RXD
13	UART_RTS#	14	UART_CTS#
15	NC	16	GND

(22) PWRIN1

Function: Power input terminal block
Connector Type: 1x3-pin Terminal block

Pin Assignment:

Pin	Desc.	
1	VCC	
2	GND	
3	D_GND	





Chapter 4

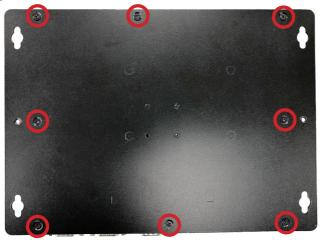
Installation & Maintenance

4.1. Disassembling and Assembling the Computer

4.1.1. Disassembling the Computer

To use onboard jumpers/connectors or to install/remove internal components, you will need to open the computer to access the inside of the computer. Follow through the guide below to disassembly the computer.

1. Position the computer with the bottom side facing up and remove 8 screws securing the chassis as shown below .



- 2. Then lift the bottom chassis away from the from the assembly.
- 3. You are ready to access the components on the main board and make required configurations and connections.



4.1.2. Assembling the Computer

After completing the required hardware installation and jumpers settings, assemble the computer by performing the proceeding steps in reverse order.

4.2. Installing Hardware

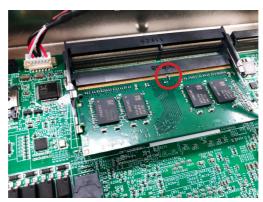
4.2.1. Installing Memory Module

The computer has two 260-pin DDR4 SO-DIMM sockets that each socket support up to 32 GB maximum system memory. To install a memory module:

1. Open the ARES-1980's case and locate memory module sockets.



2. Align the notch on the memory module with the key in the module socket.



3. Slide the module into place. Once the memory module is fully inserted into the socket, press down on the top edge of the device to latch it into place.



4. This way it's flat to the laptop's bottom. The carrier should snap into place with latches.

4.2.2. Installing/Replacing a SSD or HDD

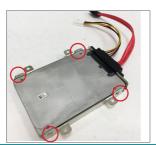
 Remove the hard drive bay from the bottom side chassis by loosening the 4 screws.



2. Slide the 2.5" HDD or SSD storage device into the drive bay and ensure it connects to the SATA connector.



3. Using 4 screws coming with the storage device kit, fix the storage device in place.



4. Connect the SATA interface and power cables to the SATA & power connectors on the main board.



5. Secure the drive bay back to the bottom side chassis by fastening the 4 screws you removed in Step 1.



4.2.3. Installing M.2 Module

The computer has a M.2 M-Key socket for NvME SSD storage. This section will use a 22 x 80 form factor as the installation example.

1. Remove the bottom cover from the computer as described in <u>4.1.1.</u> <u>Disassembling the Computer</u> on page <u>24</u>. Locate the M.2 on-board connector.



2. Insert the M.2 module into the socket by aligning the notch on the module with the small slot on the M.2 socket.



3. Insert and fasten the screw into the standoff.

4.2.4. Installing Encription Dongle

The computer has a USB 2.0 connector on the main board for the users who need additional secured encryption key installed. If an encryption dongle requirement was needed, user can use this USB connector inside the computer.

Note: The USB dimension need to be 19mm to 30mm.

1. Locate the USB connector on the main board.



2. Insert the encryption dongle and secure the rack for vibration proof.



4.2.5. Install/uninstall SIM Card and relative connection module

This section will guide you how to install SIM card and relative connection module.

- 1. Remove the bottom cover from the computer as described in <u>4.1.1.</u> <u>Disassembling the Computer on page 24.</u>
- 2. Locate the SIM card slot on the main board.



3. Slide the SIM card holder cover towards the OPEN edge and then lift the cover to open it.



4. Insert the SIM card into the card holder as shown below.



5. Close the SIM card holder door and slide the door to the LOCK edge to lock into place.



6. Locate the MC1 slot and insert the relative communication module then fasten the screw.





7. If the other SIM card is needed, please follow the steps above and install the SIM card in the second or third position as the picture.



8. Locate the MBKEY slot and insert the relative communication module then fasten the screw.



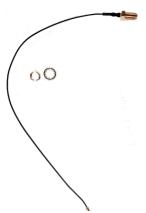


4.2.6. Install/uninstall WI-FI connection module

- 1. Remove the bottom cover from the computer as described in <u>4.1.1.</u> <u>Disassembling the Computer</u> on page <u>24.</u>
- 2. Locate the M.2 E-Key socket for wireless module.



3. Prepare the Wi-Fi module kit. The module is a **M.2 E-Key** socket form factor, with two MHF connectors, one is "MAIN", and the other is "AUX".

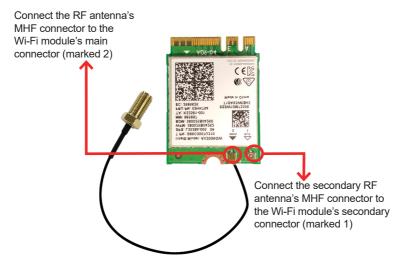


Two MHF connectors, one is "MAIN" (marked 2), the other is "AUX" (marked 1).



4. Have the RF antenna. The antenna has an SMA connector on one end and an MHF connector on the other.

5. Connect the RF antenna's MHF connector to the Wi-Fi module's main connector marked 0. If you are going to connect a secondary antenna, connect it to the connector marked



6. Plug the Wi-Fi module to the socket's connector by a slanted angle. Fully plug the module, and note that the notch on the wireless module should meet the break of the connector, then fasten the screw.



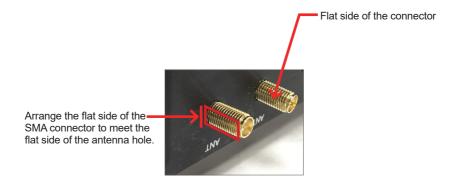
7. Locate the SMA antenna holes and. Remove the plastic plug(s) from the computer's top panel side to make antenna hole(s). Keep the plastic plug for any possible restoration in the future.



8. From the other end of the RF antenna, which is an SMA connector, remove the washer and the nut. Note the SMA connector has the form of a threaded bolt, with one flat side.



9. Pull the SMA connector through the above mentioned antenna hole. Note to meet the aforesaid flattened side with the antenna hole's flat side.



10. Mount the washer first and then the nut to the SMA connector. Make sure the nut is tightened.



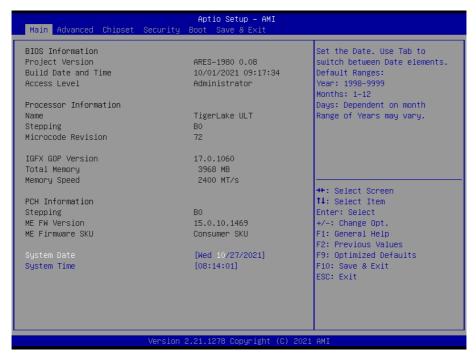
11. After completing the required hardware installation, assemble the computer by performing the proceeding steps in reverse order.

Chapter 5

BIOS

The BIOS Setup utility is featured by American Megatrends Inc to configure the system settings stored in the system's BIOS ROM. The BIOS is activated once the computer powers on. When the computer is off, the battery on the main board supplies power to BIOS RAM.

To enter the BIOS Setup utility, keep hitting the "Delete" key upon powering on the computer.



Note: Actual model name and board information varies according to your model.

Menu	Description
Main	See <u>5.1. Main</u> on page <u>42</u>
Advanced	See <u>5.2. Advanced</u> on page <u>43</u>
Chipset	See <u>5.3. Chipset</u> on page <u>59</u>
Security	See <u>5.4 Security</u> on page <u>66</u>
Boot	See <u>5.5. Boot</u> on page <u>68</u>
Save & Exit	See <u>5.6. Save & Exit</u> on page <u>69</u>

Key Commands

The BIOS Setup utility relies on a keyboard to receive user's instructions. Hit the following keys to navigate within the utility and use the utility.

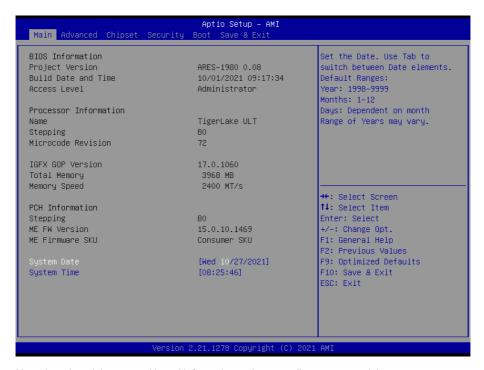
Keystroke	Function
\leftarrow \rightarrow	Moves left/right between the top menus.
↓ ↑	Moves up/down between highlight items.
Enter	Selects an highlighted item/field.
	➤ On the top menus:
Esc	Use Esc to quit the utility without saving changes to CMOS. (The screen will prompt a message asking you to select OK or Cancel to exit discarding changes.
	➤ On the submenus:
	Use Esc to quit current screen and return to the top menu.
Page Up / +	Increases current value to the next higher value or switches between available options.
Page Down / -	Decreases current value to the next lower value or switches between available options.
F1	Opens the Help of the BIOS Setup utility.
F10	Exits the utility saving the changes that have been made. (The screen then prompts a message asking you to select OK or Cancel to exit saving changes.)

Note: Pay attention to the "WARNING" that shows at the left pane onscreen when making any change to the BIOS settings.

This BIOS Setup utility is updated from time to time to improve system performance and hence the screenshots hereinafter may not fully comply with what you actually have onscreen.

5.1. Main

The **Main** menu features the settings of **System Date** and **System Time** and displays some BIOS info.



Note: Actual model name and board information varies according to your model.

Setting	Description
Project Version	Delivers the model name of the computer and BIOS version.
Build Date and Time	Delivers the date and time when the BIOS Setup utility was made/ updated.
Access Level	Delivers the level that the BIOS is being accessed at the moment.
System Date	Sets system date.
System Time	Sets system time.

5.2. Advanced



Setting	Description
CPU Configuration	See <u>5.2.1. CPU Configuration</u> on page <u>44</u>
Power & Performance	See <u>5.2.2. Power & Performance</u> on page <u>45</u>
Trusted Computing	See <u>5.2.3. Trusted Computing</u> on page <u>48</u>
ACPI Settings	See <u>5.2.4. ACPI Settings</u> on page <u>50</u>
F81966 Super IO Configuration	See <u>5.2.5. F81966 Super IO Configuration</u> on page <u>51</u>
Hardware Monitor	See <u>5.2.6. Hardware Monitor</u> on page <u>52</u>
S5 RTC Wake Settings	See <u>5.2.7. S5 RTC Wake Settings</u> on page <u>53</u>
Serial Port Console Redirection	See <u>5.2.8. Serial Port Console Redirection</u> on page <u>54</u>
USB Configuration	See <u>5.2.9. USB Configuration</u> on page <u>55</u>
Network Stack Configuration	See <u>5.2.10</u> . Network Stack Configuration on page <u>57</u>
NVMe Configuration	See <u>5.2.11. NVME Configuration</u> on page <u>58</u> .

5.2.1. CPU Configuration

Advanced	Aptio Setup – AMI	
CPU Configuration		When enabled, a VMM can
Type ID Speed L1 Data Cache L1 Instruction Cache L2 Cache L3 Cache	11th Gen Intel(R) Core(TM) i3-1115GRE @ 3.00GHz 0x806C1 3000 MHz 48 KB x 2 32 KB x 2 1280 KB x 2 6 MB Supported	hardware capabilities provided by Vanderpool Technology.
SMX/TXT Intel (VMX) Virtualization Technology Active Processor Cores Hyper–Threading	Not Supported [Enabled] [All] [Enabled]	++: Select Screen †1: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F9: Optimized Defaults F10: Save & Exit ESC: Exit
Vers	ion 2.21.1278 Copyright (C) 20)21 AMI

Setting	Description
Intel (VMX) Virtualization	When enabled, a VMM can utilize the additional hardware capabilities provided by Vanderpool Technology
Technology	► Options: Enabled (default) or Disabled
Astiva Dusassau Causa	Number of cores to enable in each processor package.
Active Processor Cores	▶ Options: All (default), 1, 2 and 3.
	This item is used to enable or disable the processor's Hyper-threading feature.
Hyper-Threading	Enabled for Windows XP and Linux (OS optimized for Hyper-threading Technology) and disabled for other OS (OS not optimized for Hyper-threading Technology).
	When disabled, only one thread per enabled core is enabled.
	Options: Enabled (default) or Disabled
	* This setting may not be available depending on the CPU.

5.2.2. Power & Performance



Setting	Description
CPU - Power Management	Configure CPU Power Management
Control	See <u>5.2.2.1 CPU Power & Performance</u> on page <u>46</u>
GT - Power Management Configure graphics processors Power Management	
Control	See <u>5.2.2.2 GT Power & Performance</u> on page <u>47</u>

5.2.2.1 CPU Power & Performance



Setting	Description	
Boot performance Mode	Set the performance state that the BIOS will set before the OS handoff.	
	Options: Max Non-Turbo Performance (default), Max Battery and Turbo Performance	
Intel (R) Speed Step (tm)	Enable (default) / Disable Intel SpeedStep	
Config TDP Configurations Configurable TDP Mode		
C States	Enable / Disable (default) CPU C States	

5.2.2.2 GT Power & Performance

Advanced	Aptio Setup – AMI	
GT – Power Management Control		Check to enable render standby
RC6(Render Standby) Maximum GT frequency Disable Turbo GT frequency	[Enabled] [Default Max Frequency] [Disabled]	++: Select Screen †1: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F9: Optimized Defaults F10: Save & Exit ESC: Exit
Version 2	.21.1278 Copyright (C) 2021	AMI

Setting	Description
RC6 (Render Standby)	Function of activation and deactivation the energy-saving mechanism integrated into the Intel graphics core processors when the computer enters sleep mode.
	Enable (default) / Disable
Maximum GT frequency	This item maximum GT frequency limited by te user. Value beyond the range will be clipped to min/max supported by SKU.
	Default Max Frequency (default)
Disable Turbo GT	This item Disable Turbo GT frequency. Enabled : Disables Turbo GT frequency. Disabled : GT frequency is no limited.
frequency	Disabled (Default) / Enabled

5.2.3. Trusted Computing

TPM 2.0 Device Found		Enables or Disables BIOS
Firmware Version:	7.85	support for security device.
Vendor:	IFX	O.S. will not show Security Device. TCG EFI protocol and
		INT1A interface will not be
Active PCR banks	SHA256	available.
Available PCR banks	SHA-1,SHA256	
SHA-1 PCR Bank	[Disabled]	
SHA256 PCR Bank	[Enabled]	
Pending operation	[None]	
Platform Hierarchy	[Enabled]	
Storage Hierarchy	[Enabled]	→+: Select Screen
Endorsement Hierarchy	[Enabled]	↑↓: Select Item
TPM 2.0 UEFI Spec Version	[TCG_2]	Enter: Select
Physical Presence Spec Version	[1.3]	+/-: Change Opt.
TPM 2.0 InterfaceType Device Select	[TIS] [Auto]	F1: General Help F2: Previous Values
Device Select	[HUTO]	F9: Optimized Defaults
		F10: Save & Exit
		ESC: Exit
		COO. EXIL

Setting	Description
Security Device Support	This item enables or disables BIOS support for security device. O.S will not show Security Device.
	Enabled (Default) / Disabled
CUA 4 DCD David	This item enables or disables SHA-1 PCR Bank.
SHA-1 PCR Bank	Enabled/Disabled(Default)
CHAOSC DOD Donk	Enables or disables SHA-1 PCR Bank.
SHA256 PCR Bank	Enabled (Default) / Disabled
Danding appeting	This item schedule an operation for the security device.
Pending operation	None (Default) / TPM Clear
Platform Hierarchy	Enables or disables Platform Hierarchy
	Enabled (Default) / Disabled
Ctanana Hismanahu	Enables or disables Storage Hierarchy
Storage Hierarchy	Enabled (Default) / Disabled

Endorsement Hierarchy	Enables or disables Endorsement Hierarchy.
Endorsement merarchy	Enabled (Default) / Disabled
	Allows user to select the TCG2 Spec Version Support.
TPM2.0 UEFI Spec Version	TCG_1_2: Compatible mode for Win8/ Win10 TCG_2: Support new TCG2 protocol and event for Win10 or later.
	TCG_1_2/TCG_2 (Default)
Physical Presence Spec Version	This item select to tell O.S. to support PPI Spec Version 1.2 or 1.3.
	1.3 (Default) / 1.2
Device Select	TPM 1.2 will restruct support to TPM 1.2 devices, TPM 2.0 will restrict support to TPM 2.0 devices, Auto will support both TPM 2.0 devices and TPM 1.2 deviced.
	Auto(Default)/TPM 1.2/TPM 2.0

5.2.4. ACPI Settings

Advanced	Aptio Setup – AMI	
ACPI Settings		Enables or Disables System ability to Hibernate (OS/S4
Enable Hibernation ACPI Sleep State	[Enabled] [S3 (Suspend to RAM)]	Sleep State). This option may not be effective with some operating systems.
		++: Select Screen †1: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F9: Optimized Defaults F10: Save & Exit ESC: Exit
V	ersion 2.21.1278 Copyright (C) 20	21 AMI

Setting	Description
Enable ACPI Auto Configuration	Enable (default) or Disable BIOS ACPI Auto Configuration
AODI Olassa Otata	Only available when BIOS ACPI Auto Configuration is enabled. Select ACPI sleep state the system will enter when the
ACPI Sleep State	SUSPEND button is pressed. Options: Suspend Disabled and S3 (Suspend to RAM) (default)

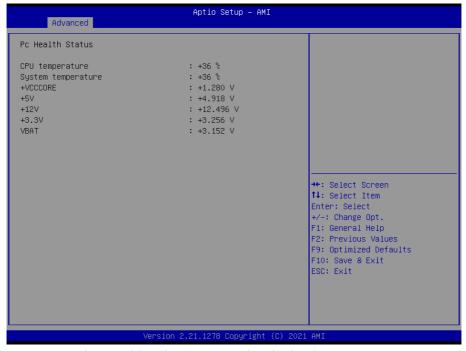
5.2.5. F81966 Super IO Configuration



Note: The quantity of serial ports varies according to your model.

Setting	Description
Serial Port 1/2/3/4 Configuration	To configure each COM port settings.
	Note: The quantity of serial ports varies according to your model.
Serial Port	Enable (default) or Disable the Serial Port (COM).
	For Serial Port 1/2:
COM1/2 Mode Select	Select RS-232 (default), RS-422, RS-485 or RS-485 with termination resistor.

5.2.6. Hardware Monitor



Access this submenu to monitor the hardware status.

5.2.7. S5 RTC Wake Settings

Advanced	Aptio Setup – AMI	
Wake system from S5	[Disabled]	Enable or disable System wake on alarm event. Select FixedTime, system will wake on the hr::min::sec specified. Select DynamicTime , System will wake on the current time + Increase minute(s) ++: Select Screen 11: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F9: Optimized Defaults F10: Save & Exit ESC: Exit
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Setting	Description
	Enable or Disable (default) system wake on alarm event.
Wake System from S5	 Options available are: Disabled (default): Fixed Time: System will wake on the hr::min::sec specified. DynamicTime: If selected, you need to set Wake up minute increase from 1 - 5. System will wake on the current time + increase minute(s).

5.2.8. Serial Port Console Redirection



Setting	Description
Serial Port Console	Allow you to enable or disable the console redirection feature.
Redirection	Enabled / Disabled (Default)
Legacy Console	Allow you to select a COM part to display redirection of Legacy OS
Redirection Settings	and Legacy OPRom Messages.

5.2.9. USB Configuration

Advanced	Aptio Setup – AMI	
USB Configuration		Enables Legacy USB support.
USB Module Version	26	AUTO option disables legacy support if no USB devices are connected. DISABLE option will
USB Controllers: 2 XHCIs		keep USB devices available only for EFI applications.
USB Devices: 1 Drive, 1 Keyboard, 1 Mouse,	2 Hubs	
Legacy USB Support	[Enabled]	
XHCI Hand-off USB Mass Storage Driver Support	[Enabled]	
USB hardware delays and time-outs:		++: Select Screen
USB transfer time-out Device reset time-out	[20 sec] [20 sec]	↑↓: Select Item Enter: Select
Device power-up delay	[Auto]	+/-: Change Opt. F1: General Help
Mass Storage Devices:		F2: Previous Values
KingstonDataTraveler 3.0PMAP	[Auto]	F9: Optimized Defaults F10: Save & Exit FSC: Fxit
		Loo. LAIC
Version 2.21.1278 Copyright (C) 2021 AMI		

Setting	Description
Legacy USB Support	Enables/disables legacy USB support.
	Options available are Enabled (default), Disabled and Auto.
	Select Auto to disable legacy support if no USB device are connected.
	Select Disabled to keep USB devices available only for EFI applications.
XHCI Hand-off	This is a workaround for OSes without XHCI hand-off support. The XHCI ownership change should be claimed by XHCI driver.
	► The optional settings are: Enabled (default) / Disabled .
USB Mass Storage	Enables/disables USB Mass Storage Driver Support.
Driver Support	➤ The optional settings are: Enabled (default) / Disabled.
USB hardware delay and time-out	

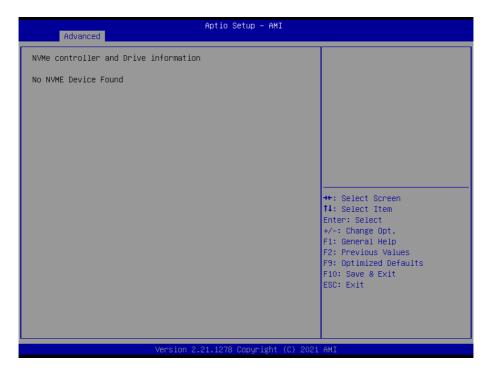
USB transfer time-	Use this item to set the time-out value for control, bulk, and interrupt transfers.
V	➤ Options: 1 sec, 5 sec, 10 sec, 20 sec (default)
Device reset time-	Use this item to set USB mass storage device start unit command time- out.
out	▶ Options available are: 10 sec, 20 sec (default)., 30 sec, 40 sec
	Use this item to set maximum time the device will take before it properly reports itself to the host controller. 'Auto' uses default value: for a root port it is 100 ms, for a hub port the delay is taken from hub descriptor.
Device power-up delay	Options available are: Auto: Default Manual: Select Manual you can set value for the following sub-item: 'Device Power-up delay in seconds', the delay range in from 1 to 40 seconds, in one second increments.

5.2.10. Network Stack Configuration



Setting	Description
Network Stack	Enable or Disable (default) UEFI network stack.

5.2.11. NVME Configuration



Access this submenu to view the NVMe controller and driver information.

5.3. Chipset



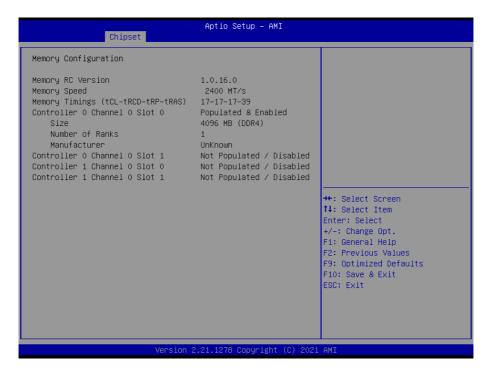
Submenu	Description
System Agent (SA) Configuration	See 5.3.1. System Agent (SA) Configuration on page 60
PCH-IO Configuration	See <u>5.3.2. PCH-IO Configuration</u> on page <u>63</u>

5.3.1. System Agent (SA) Configuration



Submenu	Description
System Agent (SA) Configuration	
Memory Configuration	See <u>5.3.1.1. Memory Configuration</u> on page <u>61</u>
Graphics Configuration	See <u>5.3.1.2. Graphics Configuration</u> on page <u>62</u>
VT-d	Enable (default) or Disable VT-d function

5.3.1.1. Memory Configuration



Access this submenu to view the memory configuration.

5.3.1.2. Graphics Configuration



Note: This page varies according to your model.

Setting	Description
Aperture Size	Select the Aperture Size ▶ Options: 128MB, 256MB (default), 512MB and 1024MB.
DVMT Pre-Allocated	Select the DVMT 5.0 Pre-allocated (Fixed) Graphic Memory size used by the Internal Graphic Device. • 60M is the default.
DVMT Total Gfx Mem	Select the DVMT 5.0 Total Graphic Memory size used by the Internal Graphic Device. Device: 128MB, 256MB (default) and Max.

5.3.2. PCH-IO Configuration



Setting	Description
PCI Express Configuration	See 5.3.2.1. PCI Express Configuration on page 64
SATA And RST Configuration	See 5.3.2.2. SATA And RST Configuration on page 82
Power on after power fail	Specify what state to go to when power is re-applied after a power failure (G3 state). Doptions available are Enable (default), Disable.

5.3.2.1. PCI Express Configuration

Aptio Setup – AMI Chipset	
PCI Express Configuration	PCI Express Root Port Settings.
► M.2 B-Key ► Intel LAN 1225LM ► Intel LAN 1211 ► Intel LAN 1211 ► Mini Card	
	++: Select Screen †1: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F9: Optimized Defaults F10: Save & Exit ESC: Exit
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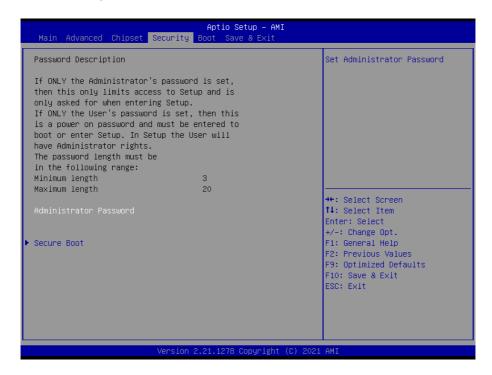
Setting	Description
M.2 B-key	PCI Express root port setings. Control the M.2 B-key root port.
Intel LAN I225LM	PCI Express root port setings. Control the LAN I225LM root port.
Intel LAN I211	PCI Express root port setings. Control the LAN I211 root port.
ASPM Support	Disable or set the ASPM level. Force L0s will force all inks to L0s state. "Auto" will allow BIOS to auto configure. "Disable" will disable ASPM.
	▶ Options: Disabled (default), L0s , L1 , L0sL1 and Auto .
PCIe Speed	Select PCI Express port speed.
	Options: Auto (default), Gen1, Gen2 and Gen3

5.3.2.2. SATA And RST Configuration



Setting	Description
SATA Controller(s)	Enables (default) / disables SATA device(s).
Aggressive LPM Support	Enables (default) / disables PCH to aggressively enter link power state.
SATA Mode Selection	Configures how SATA controller(s) operate.
	Options: AHCI (default) and Intel RST premium With Intel Optane System Acceleration.
Serial ATA Port 0/1	SATA device information.
	*Available SATA ports depend on your model.
Port 0/1	Enables (default) / disables the SATA port.
SATA Port 0/1 DevSlp	Enables / disables (default) the SATA port DevSlp. Board rework for LP needed before enable.

5.4. Security



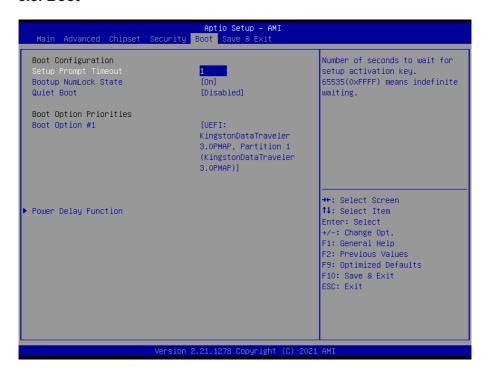
Setting	Description
	To set up an administrator password:
	Select Administrator Password.
Administrator	An Create New Password dialog then pops up onscreen.
Password	3. Enter your desired password that is no less than 3 characters and no more than 20 characters.
	4. Hit [Enter] key to submit.
Security Boot	See 5.4.1 Security Boot on page

5.4.1 Security Boot



Setting	Description
Secure Boot	Enable/Disable (default) secure boot.
Secure Boot Mode	Allow users to set the secure boot selector.
Secure Boot Mode	Standard/Custome (default) mode.
Restore Factory Keys	Force system to restore default secure boot key database.
Reset to Setup Mode	Delete all secure boot key databases.
Key Management	Allow users to modify secure variables and set key management page.

5.5. Boot



Setting	Description
Setup Prompt Timeout	Set how long to wait for the prompt to show for entering BIOS Setup.
	➤ The default setting is 2 (sec).
	Set it to 65535 to wait indefinitely.
Bootup NumLock State	Sets whether to enable or disable the keyboard's NumLock state when the system starts up.
	▶ Options available are On (default) and Off .
Quiet Boot	Sets whether to display the POST (Power-on Self Tests) messages or the system manufacturer's full screen logo during booting.
	Select Disabled to display the normal POST message, which is the default.
Boot Option Priority	Set the system boot priorities.

Power Delay Function

Set the system support power delay function.

Options:

Enable (default): Support power delay function. **Disable**: Power on/off manually operated.

Power on delay

Power Delay Function

Select the time which the system will power on.

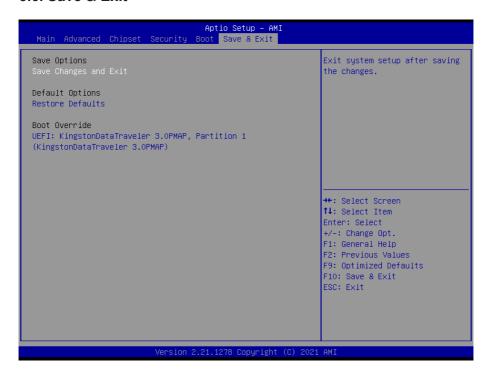
Options: Manually Operator (default), 04 Seconds, 08 Seconds and 16 Seconds.

Power off delay

Select the time which the system will shutdown.

 Options: Manually Operator (default), 30 Seconds, 60 Seconds and 90 Seconds.

5.6. Save & Exit



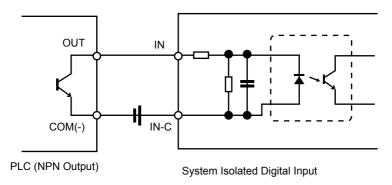
Setting	Description
Save Changes and Exit	Saves the changes and quits the BIOS Setup utility.
Restores all settings to defaults.	
Restore Defaults	▶ This is a command to launch an action from the BIOS Setup utility.
	Boot Override presents a list in context with the boot devices in the system.
Boot Override	▶ P0: Select the device to boot up the system regardless of the currently configured boot priority.
	► Launch EFI Shell from filesystem device: Attempts to launch EFI Shell Application (Shell.efi) from one of the available filesystem devices.

Appendix

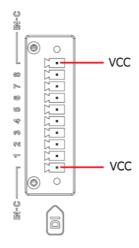
Appendix A. 16-bit DIO Signal Connections

A.1. Isolated Digital Input Connections

The input (IN-C) will accept supply voltages. Make sure the Von (IN-C to IN) is more than 12V and Voff (IN-C to IN) is less than 5V. The following diagram shows the connection between outside signal and the system.

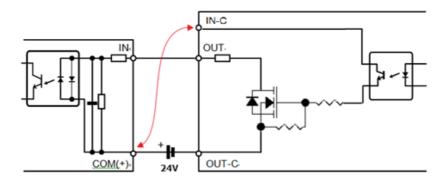


Note that the input's (IN-C) first and last pins are for VCC.



A.2. Isolated Digital Output Connections

When an isolated output channel is being used as an output channel, if an external voltage is applied, the current will flow from the external voltage source to the system. Make sure that the current through each out pin does not exceed 100 mA.



Note that the output's (OUT-C) first and last pins are for GND.

